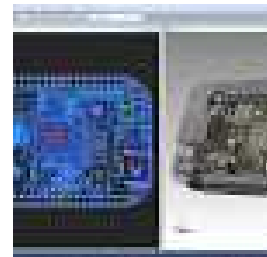




# 코스텍시스템 제품 소개





# EFEM

---

1. EFEM
2. ATM Robot
3. Pre Aligner
4. LPM(N2 Purge)



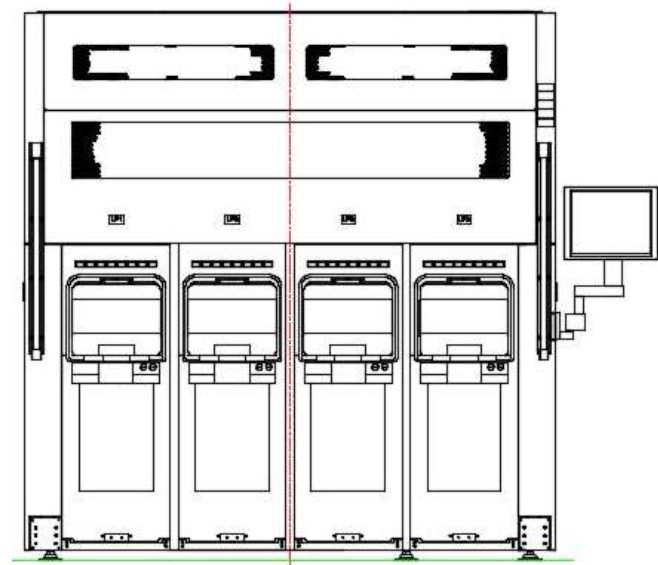
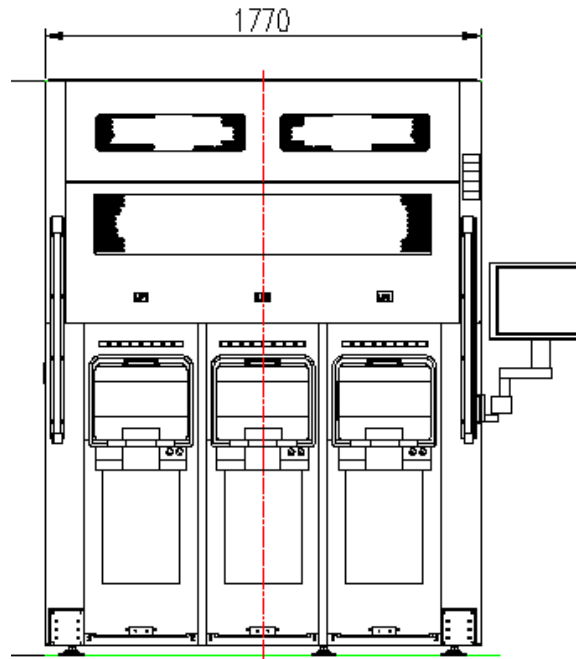
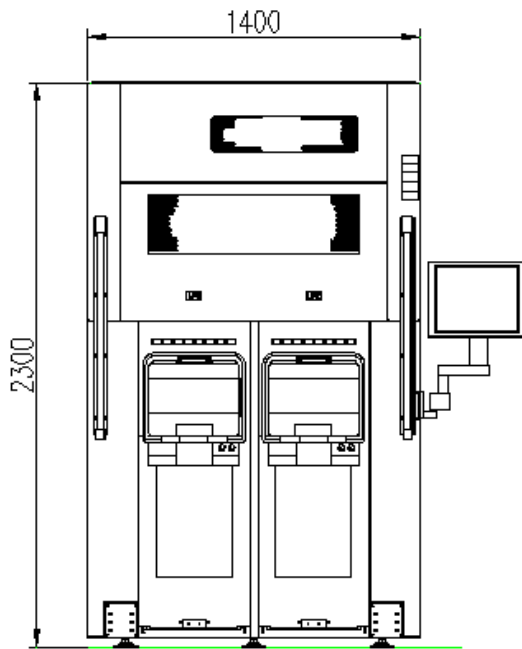
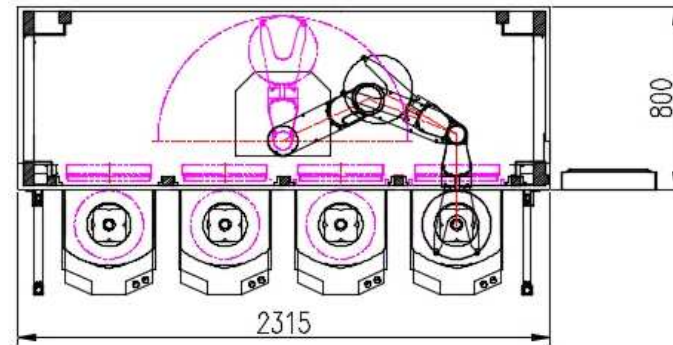
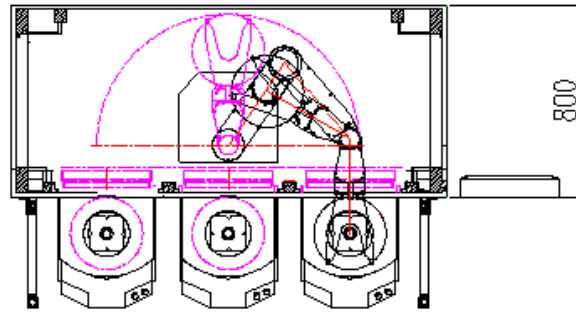
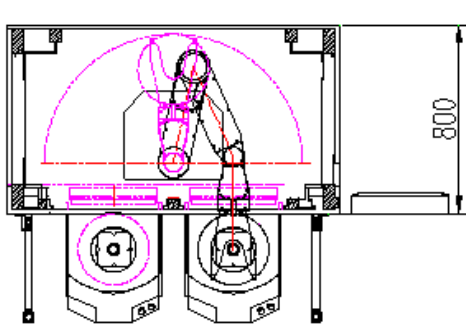
**Kostek's EFEM performs highly accurate, safe wafer transfer, efficient wafer alignment and ID reading.**

- **Variety atmospheric robots and pre-aligners adoptable single arm, dual arm, flip robot, etc.**
- **Passive end effector with GN-PAD**  
→
- **Automatic and accurate wafer alignment with several types of pre-aligners.**
- **Reliable load port modules & N2 purged FOUP(option).**
- **Samsung & SK Hynix spec. satisfaction in accordance with SEMI standard**
- **Easy integration with all process and metrology equipment.**





# EFEM (Typical Layout)



**2 LPMs**

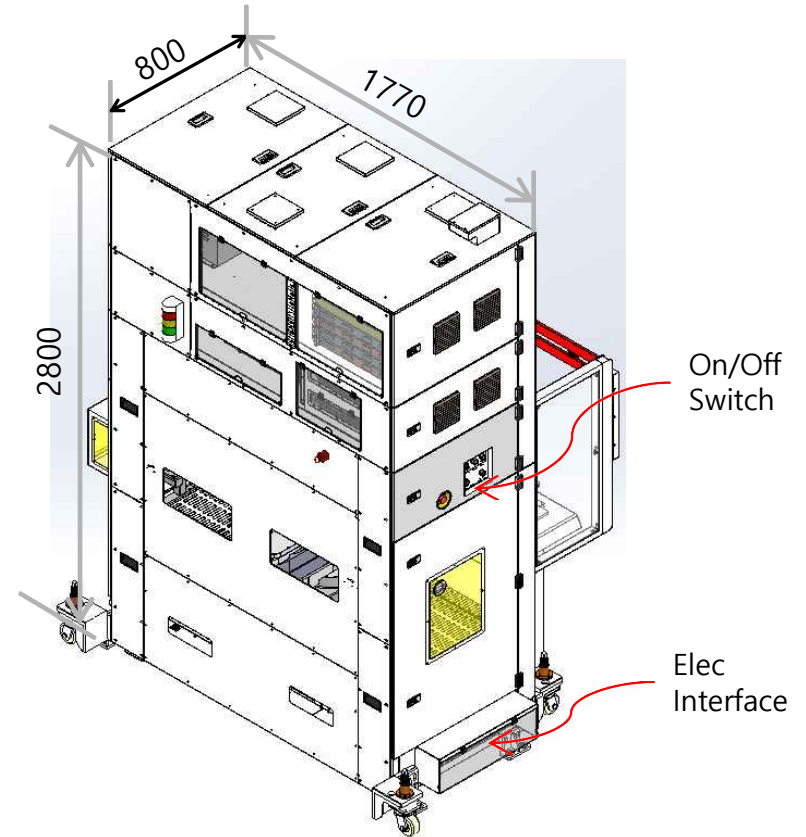
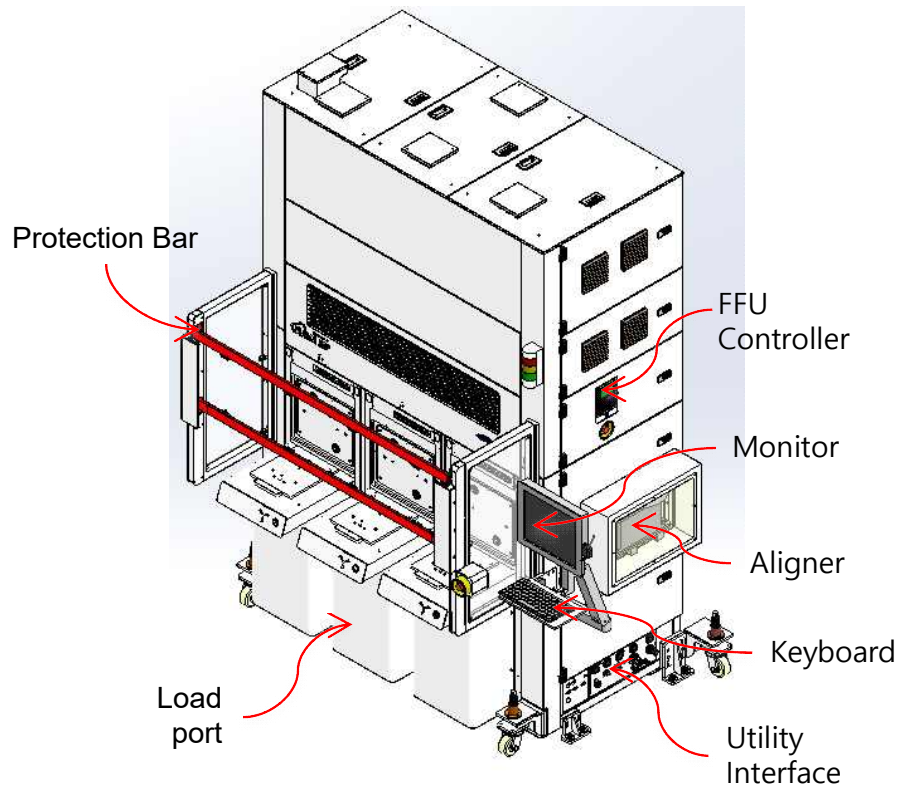
**3 LPMs**

**4 LPMs**





# EFEM (Description)



**Foot Print (mm): 800 x 1770 x 2800**



# EFEM (Specifications)



ITEMS		SPECIFICATIONS
General	Wafer size	300mm Silicon Wafer
	Carrier	25 Wafers FOUP
	Color	White : EX4511(S)-WH0009
	Load port	300mm LPM(3 FOUP)
	Light	LED
	Display Monitor	LCD Touch Monitor
Environment	Internal Pressure monitoring	Diff. pressure display, Interlock
	Operation Environment	Class 1 clean room
	Particle Performance	$\leq 2.0ea / \leq 0.45nm$
	Filter Material	PTFE ULPA Filter (Chemical Filter)
	Filter Pressure Drop(Pa)	<39.2 (Velocity based) <93.2 (Velocity based)
Safety	Signal Tower Lamp	(Red/Green/Yellow) + Buzzer
	EMO	3 EA (Front / Left / Right)
	Light curtain	Dual Protection Bar
Utility	CDA	3/8", $\geq 5 \text{ kgf/cm}^2$
	Vacuum	$\leq - 80 \text{ Kpa}$
	Power	208 VAC, 30A + GND

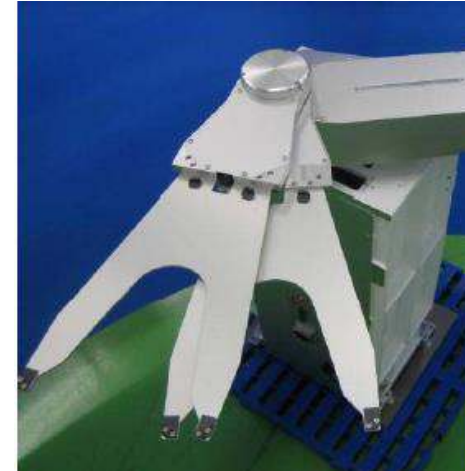




# ATM ROBOT



- ATM robot for various makers
- Anti-Corrosion
- AWC  $\pm 0.1\text{mm}$
- Auto teaching function
- Self-diagnosis function



RobotSupportTool : LifeCycle Maintenance

File Edit View Setting Maintenance Status Help

LifeCycle Monitor Last updated on 2019/06/03 19:23:17

No.	Item Name	Begin	p-day	p-hour	Elasped	Next
01	BALL SCREW GREASE UP	2018/01/01 00:00	182	0	285.1%	2018/07/02 00:00
02	GUIDE RAIL GREASE UP	2018/01/01 00:00	182	0	285.1%	2018/07/02 00:00
03	OVERHAUL	2018/01/01 00:00	730	0	71.1%	2020/01/01 00:00
04	M1 GEAR CHANGE	2018/01/01 00:00	730	0	71.1%	2020/01/01 00:00
05	M2 GEAR CHANGE	2018/01/01 00:00	730	0	71.1%	2020/01/01 00:00
06	M3 GEAR CHANGE	2018/01/01 00:00	730	0	71.1%	2020/01/01 00:00
07	M4 GEAR CHANGE	2018/01/01 00:00	730	0	71.1%	2020/01/01 00:00
08	M1 MOTOR CHANGE	2018/01/01 00:00	2920	0	17.8%	2025/12/30 00:00
09	M2 MOTOR CHANGE	2018/01/01 00:00	2920	0	17.8%	2025/12/30 00:00
10	M3 MOTOR CHANGE	2018/01/01 00:00	2920	0	17.8%	2025/12/30 00:00
11	M4 MOTOR CHANGE	2018/01/01 00:00	2920	0	17.8%	2025/12/30 00:00
12	MAINBOARD CHANGE	2018/01/01 00:00	2920	0	17.8%	2025/12/30 00:00

Read Write

Ready not connected.





# Pre Aligner

ITEMS	SPECIFICATIONS
Wafer Size	300mm
Detection Target	Notch
Wafer Material	Silicon or Quartz
Detection sensor of wafer edge	LED + CCD line sensor
Alignment Precision	$\pm 0.03\text{deg}$
Alignment time	Under 1.7 sec
Clean class	ISO Class 1
MCBF	Over 15,000,000 Cycle
Weight	5.8kg




- Compact size and buried controller in robot
- Minimized installation area of EFEM
- Minimized dead zone area in robot motion
- Realized high resolution and speed through algorism improvement





## STD LPM(KOREL 550)

- Compliance with SEMI, CE, and fab requirements.
- 
- Easy positioning mechanism to reduce installation time for mounting and dismounting.

ITEMS		SPECIFICATIONS
Carrier type		SEMI Compliance FOUP
Dimension		472(W) x 493(D) x 1,344.5(H)
Weight		60kg
FOUP Door Opening Time	Without Mapping	≤ 12 sec
	With Mapping	≤ 15 sec
MCBF (Mean Cycles Between Failures)		≥ 100,000 Cycles
Cleanliness		ISO Class1 compatible
Electrical interface		+24V DC
Utility requirement	Vacuum	-70 kPa
	CDA	0.5 MPa
Option		RF ID Reader, PIO Sensor





## N2 Purge LPM(KOREL 550P)

ITEMS	SPECIFICATIONS
Applicable FOUP	300mm FOUP (Entegris, Shin-Etsu) SEMI E47.1/E62 compliant
Stroke	Y-axis : 70mm (SEMI Standard) Z-axis : 350mm
Repetition Precision	Y-axis : $\pm 0.1$ mm Z-axis : $\pm 0.1$ mm
Operation Time	No mapping    FOUP open : 15 sec FOUP close : 15 sec Mapping        FOUP open : 25 sec FOUP close : 15 sec
Weight	75kg
Input Power	AC220 $\pm$ 5%/3A (Full-load current : 2A)
Utilities Requirements	CDA : 0.52MPa~0.6MPa , 5L/min Vacuum : 30kpa~50kpa , 10L/min
Cleanliness	Class 1 at 0.1 $\mu$ m
Environmental	Operating Temperature : -10 ~ 55 $^{\circ}$ C Operating Humidity : 30 ~ 80%
Acoustic Noise	$\leq$ 60dB
Driving area	Stage, Door(in/out) : Cylinder Door(up/down) : Servo Motor





## **Vacuum cluster tools**

---

- 1. Twinstar / Maxima / Optima**
- 2. Vacuum Robot**
- 3. Load Lock**
- 4. Furnace Variable Pitch Robot**
- 5. Customized Models**



# Vacuum Cluster Tools



**Kostek** has been providing various vacuum cluster tools since 2001 to major domestic semiconductor equipment suppliers.

**Twinstar™**, **Maxima™** and **Optima™** are key modules for the semiconductor equipment and have been showing reliable wafer transfer and vacuum performance in various applications such as CVD, ALD, Etch.

More than 1200 systems are installed, Kostek is ranked as top of a semiconductor equipment automation tool providers in Korea, and is ready to expand its territories to world market.





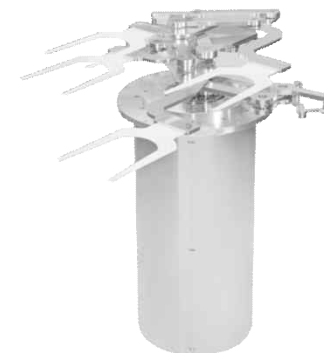


The Twinstar is designed for an optimized twin wafer process with an excellent performance and high throughput.

It can attach up to 3 twin process modules.

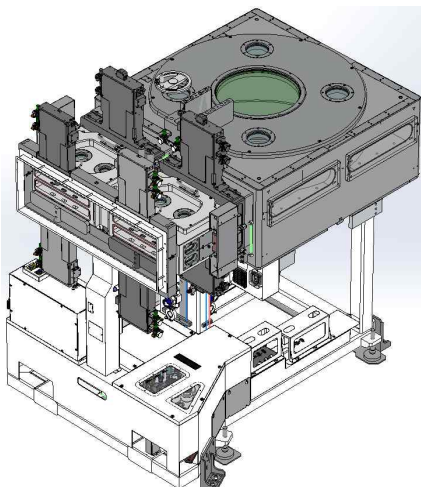
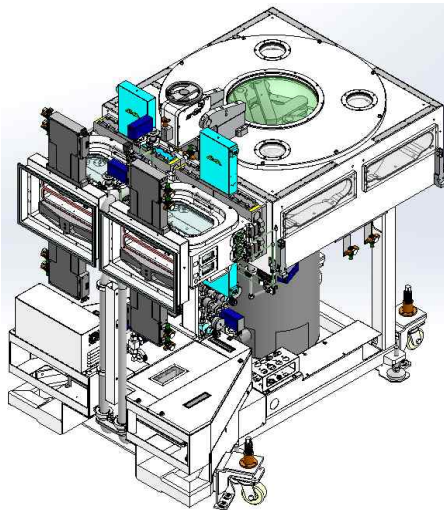
## Key Features

- High throughput and reliability by using specially designed 6 axes vacuum robot with AWC
- Configurable up to 3 twin process modules
- Duplex design and high throughput load lock chamber
- Wafer pre-heating unit(option)
- Suitable for CVD and Dry Etch & ALD processes
- Compatibility of SEMI / MESC
- Satisfaction of CE Mark and SEMI S2
- Wafer placement repeatability :  $\leq \pm 0.1$  mm
- Base Pressure :  $10^{-3}$  Torr (Available for  $10^{-8}$ Torr)
- Particle :  $\leq 5$  ea @0.16um
- MCBF :  $\geq 100,000$  cycles
- UPEH : 307 wafers/hr

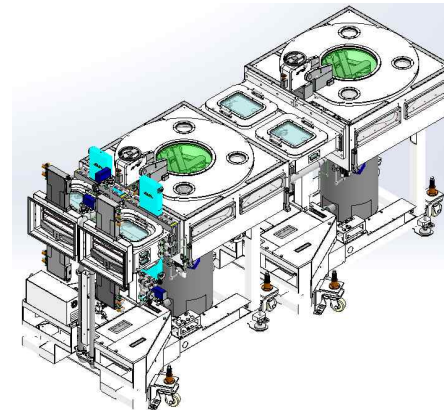




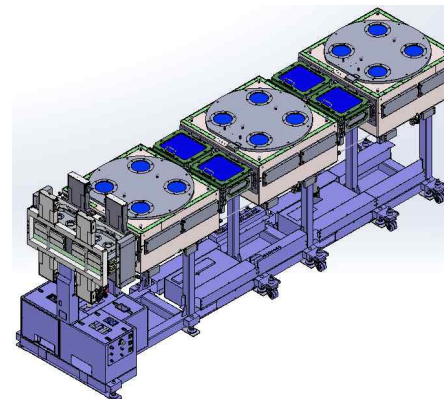
## Twinstar – 3 Series (For CVD process)



## Twinstar – Tandem (For Mold process)



## Twinstar – Guard





**Kostek's Maxima series are optimized for excellent performance and high throughput.**

**The system can be attached up to 7 process modules.**

## Key Features

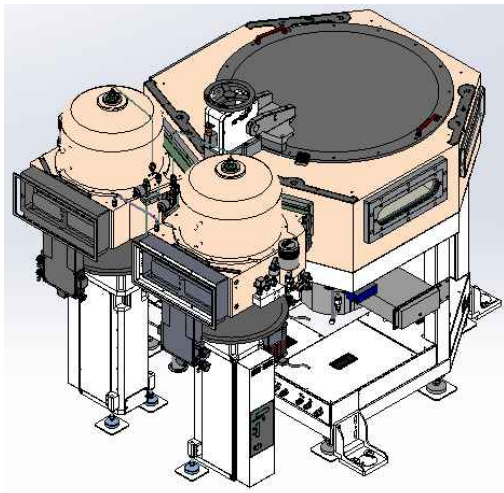
- Up to 8 sided transfer chamber
- 2 slotted LL or 25 wafers batch LL
- Integrates pre-heat and post cool into LL chamber(option)
- Field proven vacuum robot with AWC feature
- Wafer Placement repeatability :  $\leq \pm 0.1$  mm
- Base Pressure :  $10^{-3}$ Torr(Available for  $10^{-8}$ Torr)
- Particle :  $\leq 5$  ea @0.16um
- UPEH : 148 wafers/hr
- Compatibility of SEMI / MESC
- Satisfaction of CE Mark and SEMI S2



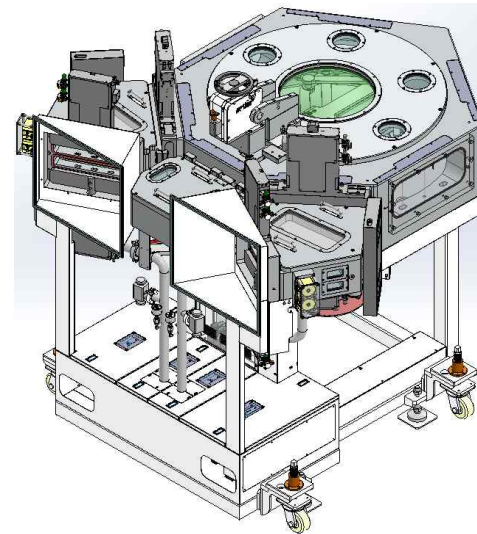


## High Throughput systems

**Maxima 3700 with 2 Batch LLs**



**Maxima 3700 with 4 LLs**







**Kostek's Optima series are optimized for excellent performance and high throughput.**

**The system can be attached up to longer process time modules.**

## Key Features

- Variety configurations up-to 4 PMs for 300mm wafer
- High throughput available with dual transfer module for various processes
- Suitable for long process time such as ALD
- Field proven vacuum robot with AWC feature
- Wafer Placement repeatability :  $\leq \pm 0.1$  mm
- Base Pressure :  $10^{-3}$ Torr(Available for  $10^{-8}$ Torr)
- Particle :  $\leq 5$  ea @0.16um
- UPEH : 152 wafers/hr
- Compatibility of SEMI / MESC
- Satisfaction of CE Mark and SEMI S2





- **Quad Arm vacuum robot for easy to combine twin process modules(7 axes)**
- **High throughput and minimized footprint of L-motion vacuum robot for single process module(5 axes)**
- **High precise of dual arm vacuum robot with rapid motion speed and longevity (4 axes)**



- **Stacked load lock chambers**
- **2 wafers loading per LL**
- **Improved throughput**
- **Fast pumping down of 7 sec**
- **Fast venting time of 9 sec**
- **Detection sensors to detect wafer**  
**dropped in the slit valve and door valve**
- **Cooling down plate for wafer post cooling**
- **Vacuum valves inserted to chamber**





# Furnace Variable Pitch Robot



Item		WTR
Axes		5-Axes (V / R2 / R1 / T / Z)
Operation range	V	5.5 ~ 25 mm
	R1/R2	440 mm(
	T	±120 deg
	Z	1350 mm
Mass		Robot 85 kg or less Elevator 55 kg or less
Motor		AC Servo motor Battery-less Absolute encoder (V:50W, R1/R2:100W, T:200W, Z:400W)
Utility	CDA	0.4 MPa ~ 0.5 MPa 30 L / min or more Φ 6 One-touch fitting 1 lines
	Vacuum	-80 kPa or less 50 L / min or more Φ 6 One-touch fitting 3 lines Φ19 Pipe 1 lines

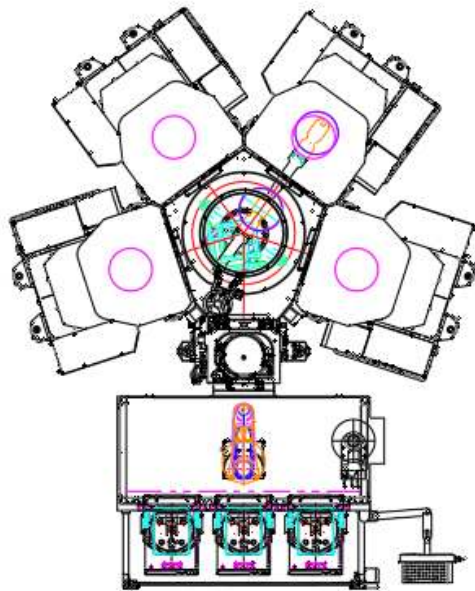




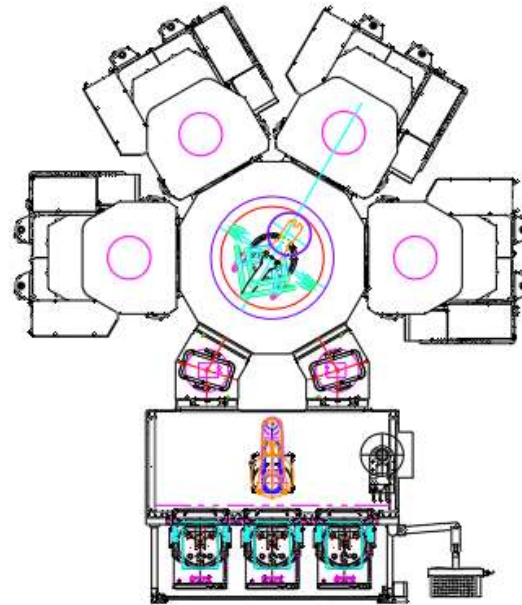


# Customized Models

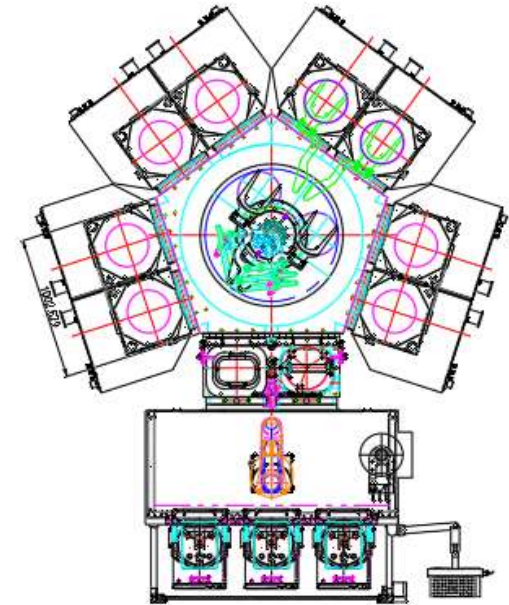
Various backbone is available depending on PM's requirement



5 sided TM  
Stack LL



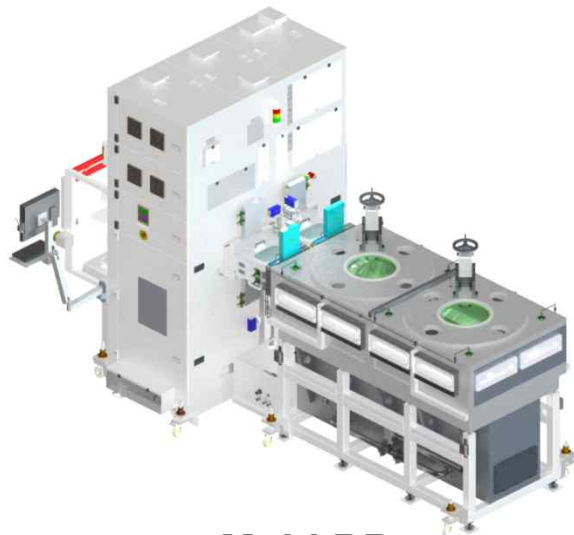
6 sided TM



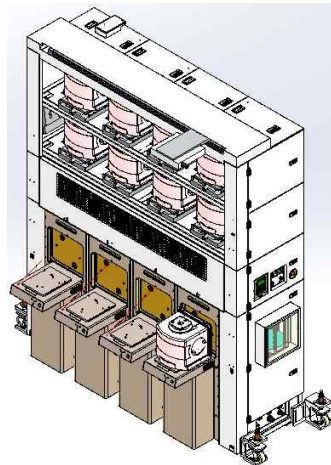
5 sided TM  
Twin PM



# Customized Models



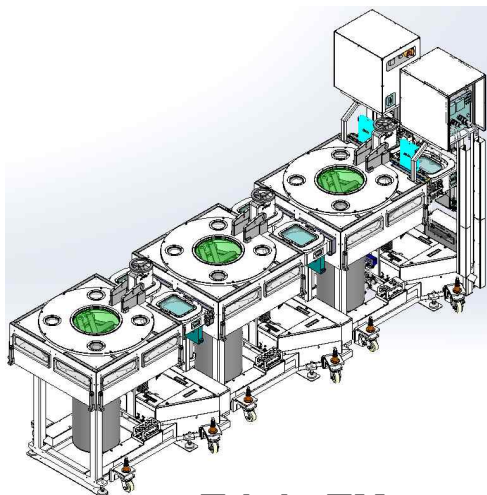
**Multi BB**



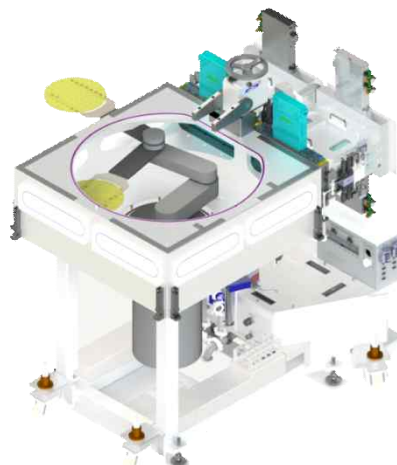
**FOUF Stacking EFEM**



**BB for single process module**



**Triple TM**



**BB with L Motioned Robot**



**BB for twin process**



# Micro LED Systems

Chip Pre-transfer System

Aligner & Pre-bonder

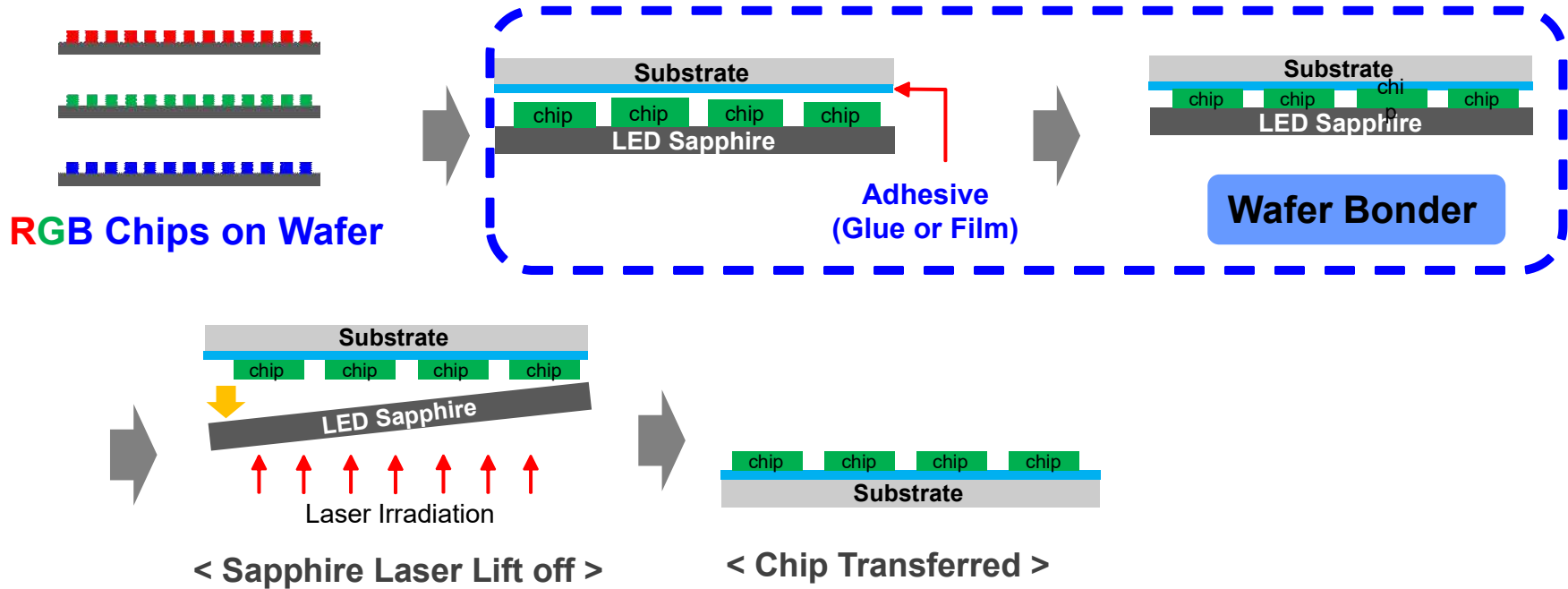
Chip Array bonder ( Thermal / Laser )





# Chip Pre-transfer Process

## Chip Pre-transfer Process flow



**Substrate : Wafer type, panel type available**

**Adhesive type : Film & Glue adhesive available**

**Film type : by Lamination, Glue type : by Spin coating**

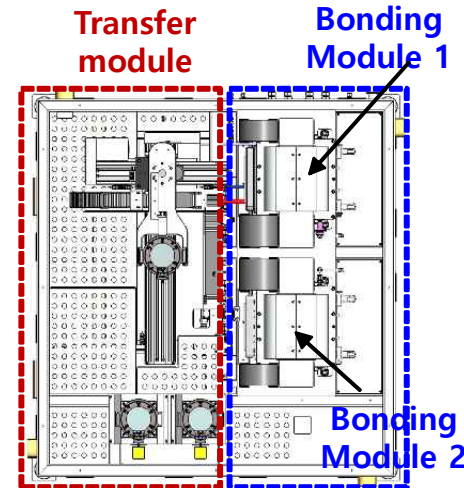


# Pre-transfer System



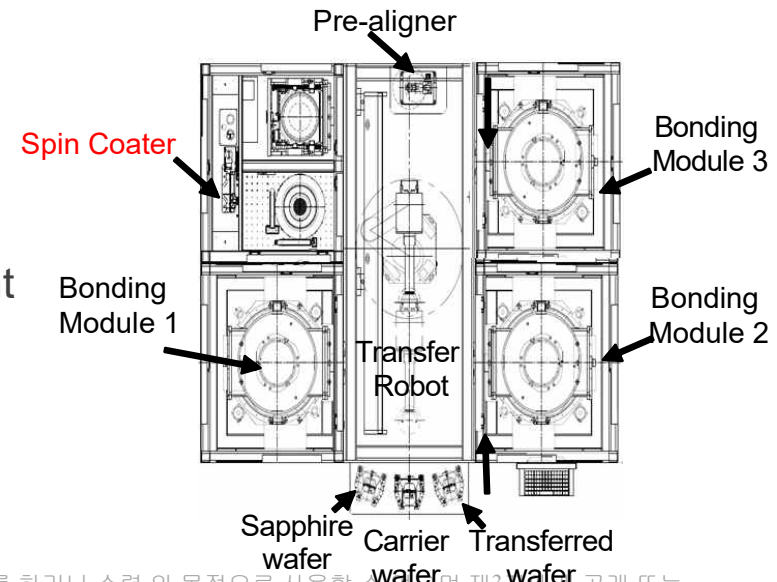
## TAURUS 100 WB

- Auto Bonding System (2 bonding modules)
- Chuck to chuck Parallel Accuracy :  $\leq 5\mu\text{m}$
- Heater Temperature : Max.  $300\text{ }^\circ\text{C} \pm 2\%$ ,
- Ramp up/down:  $30\text{ }^\circ\text{C}/\text{min}$



## Mass Production System

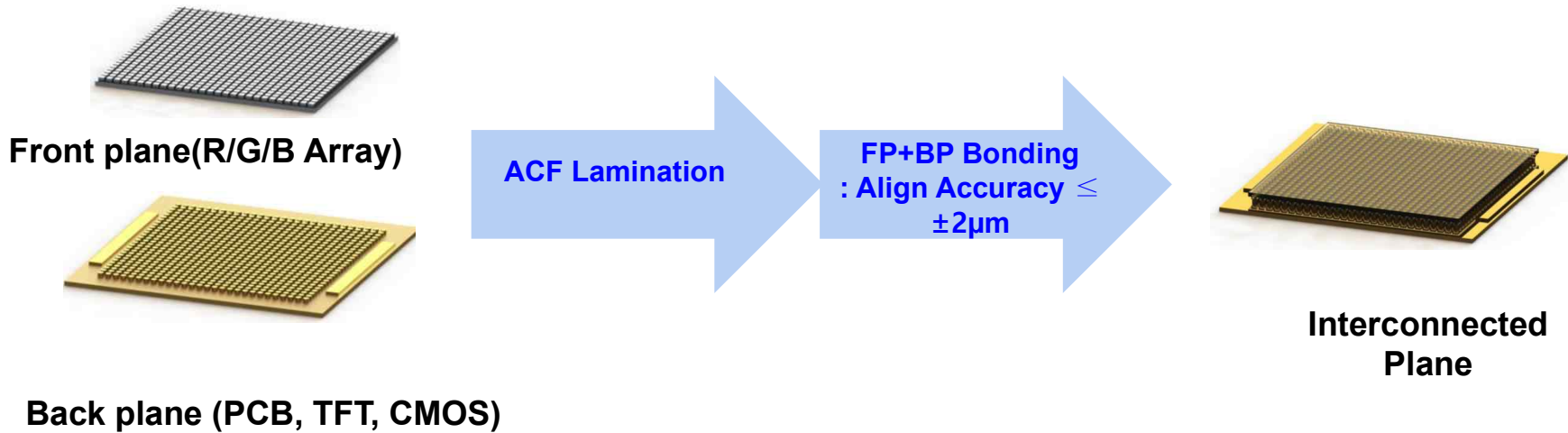
- 1 Spin coater & HP, 3 Bonding modules
- Process stabilization and productivity improvement through continuous process after PDMS coating







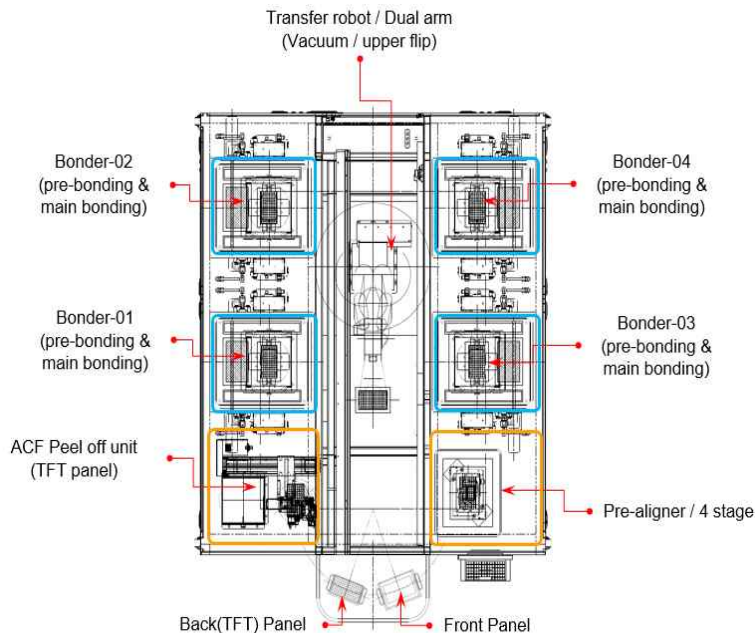
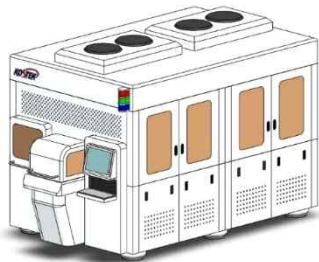
## Bonding of Front plane and Back plane



**Align accuracy**  
 **$\leq \pm 2\mu\text{m}$  @ Chip size 30~50um :**



# Aligner & Bonder(Large Sub.)



## Feature

- Full auto Aligning & Pre-bonding System
- Panel Size : 7.7inch ~ 13.5inch
- Composition
  - Bonding module : 4sets
  - Square panel pre aligner : 4sets
  - Cover film peel off unit : 1set
  - Align accuracy :  $\leq \pm 2\mu\text{m}$
  - Throughput : 40wafers/hr (per 4 chambers)

## Advantage

- Auto parallel control between Chuck to Chuck  
: Excellent pressing uniformity
- Atm. and vacuum process available
- Anti-vibration structure of the whole facility

**Process engineering available by a demo equipment!!**

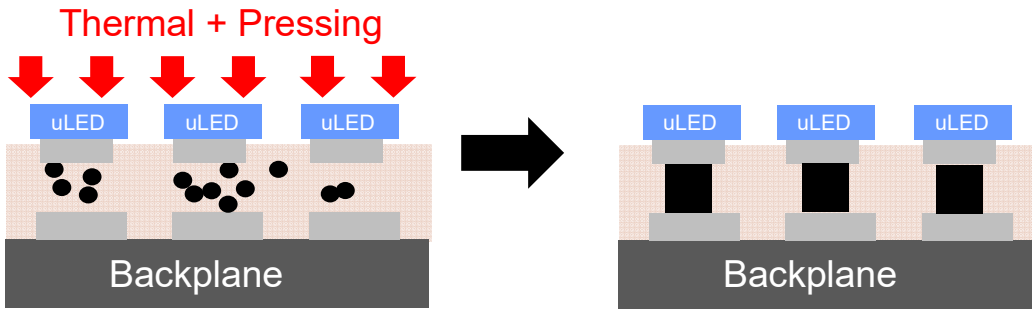


# Thermal Soldering Process Flow



As LED chip size become smaller, an advanced ACF must be developed: **Self Align Property**

→ Co-working with **ACF (SACA) technology owners** applicable to **10um** electrode sizes



Thermal Soldering

Final





# Thermal Soldering System

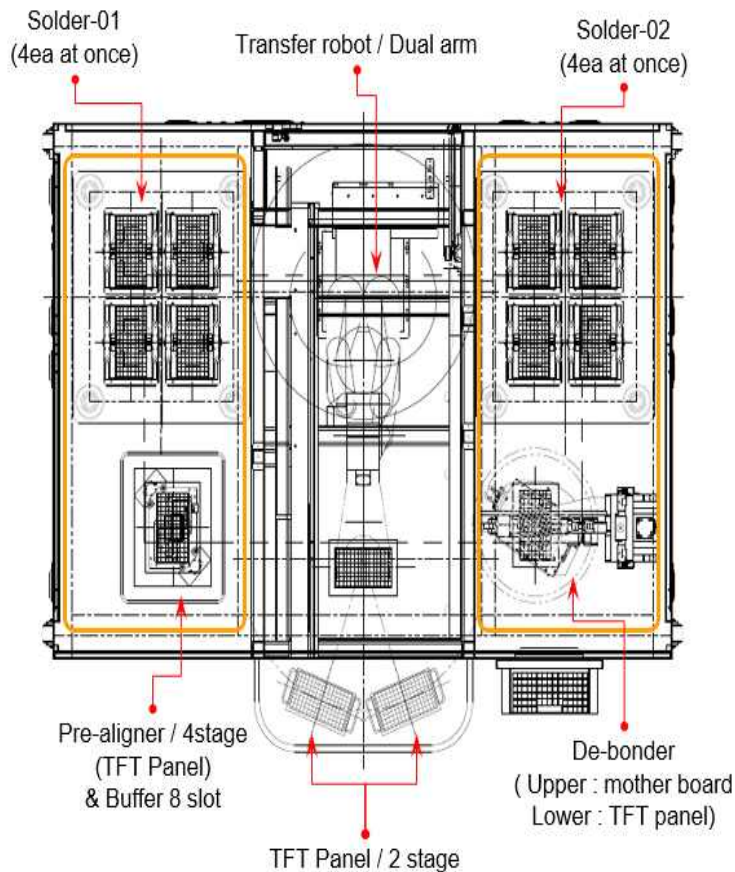


## Feature

- Thermal soldering system
  - Soldering module : up to 4 stages
- Process Specification
  - Chuck to chuck parallel accuracy :  $\leq 5\mu\text{m}$
  - Pressing force : Max. 30kN
  - Temp. ramp up/down :  $\sum 100^\circ\text{C}/\text{min}, 50^\circ\text{C}/\text{min}$
  - Throughput :  $\geq 30$  subs/hr (Process Temp.  $300^\circ\text{C}$ )  
(Depending on material's property)

## Advantage

- Low thermal expansion by using fast Heating/Cool
- Chip shift free (no chip rotation/tilting during process)
- Optimized modules configuration for high productivity
- Optimal design of bonding module for pressing force and Temp. uniformity  $\rightarrow$  Minimize process defect



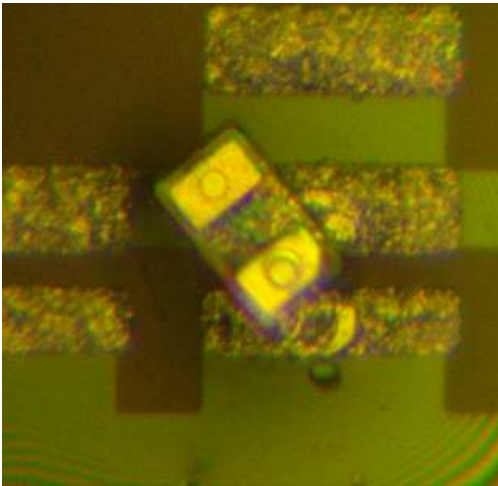




# Thermal Soldering Results



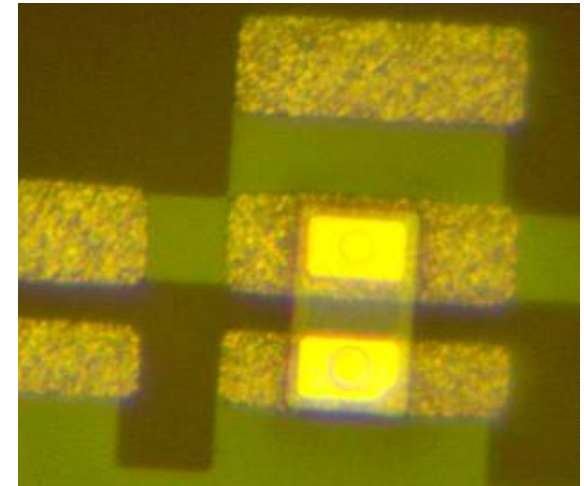
## Bad Result



- Chip Shift
- Bad Conductive Chip on BP



## Good Result



- Non Chip Shift
- Good Conductive Chip on BP

Temp./Pressing force control  
→ Good parallel accuracy

1. Fast Heating and cool down(Special Ceramic Heater)

→ Preventing Thermal Expansion

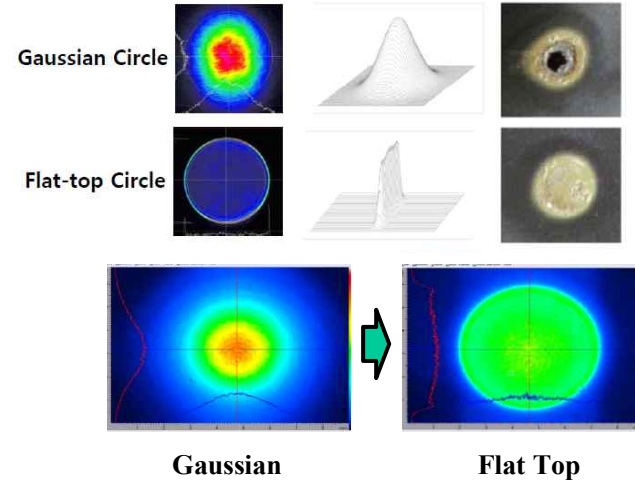
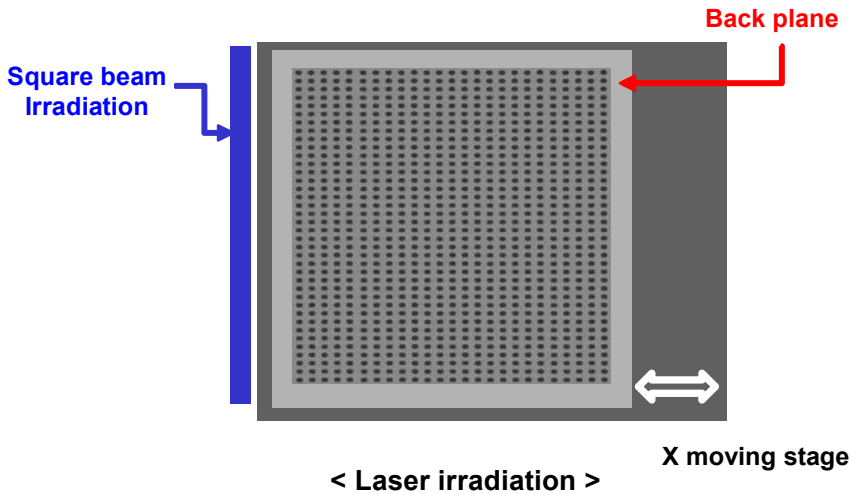
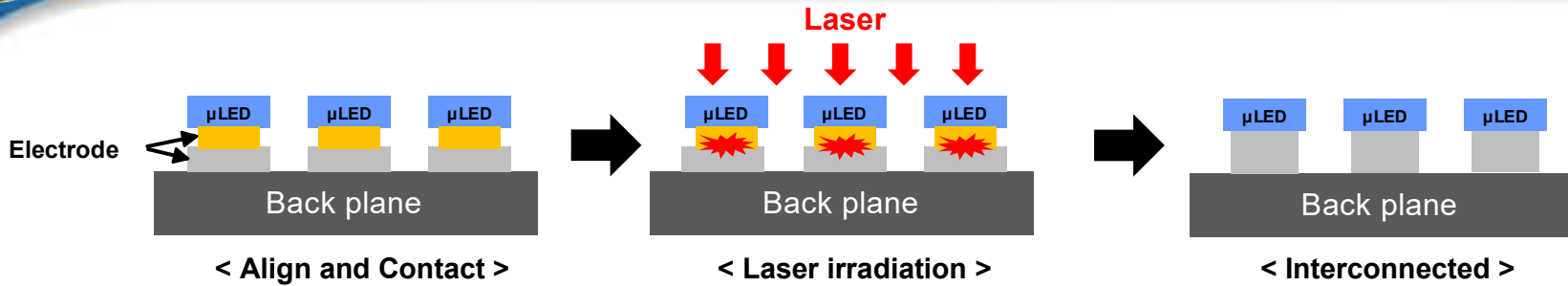
2. Pressing Force Control and Parallel Accuracy (Kostek System's unique structure)

→ Preventing bad ohmic contact and difference of the chip height after process



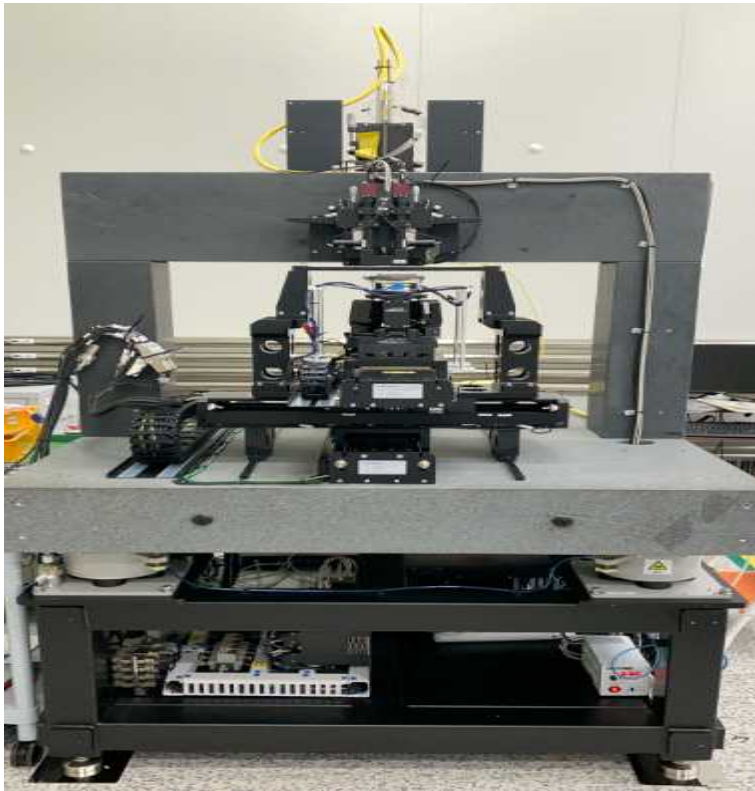


# Laser Soldering System



## Feature & Specification

- Flat top function adopted to irradiate uniform energy
- Laser : IR 1070nm
- Laser power uniformity(>80%)



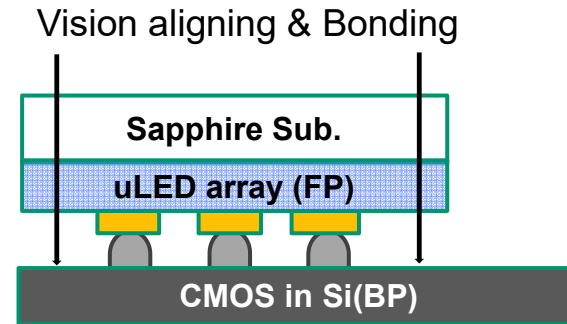
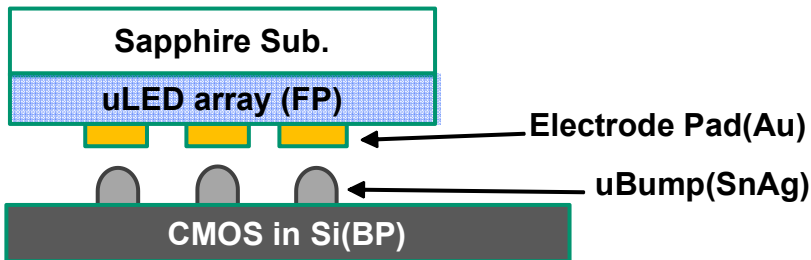
## Feature

- Eutectic Bonding by using Laser for low CTE
- Bump & ACF Process available
- Align Accuracy:  $\pm 0.5\mu\text{m}$
- Pressing force Max. :  $\sim 3\text{kg}$  force  
Heater Max. :  $\sim 200^\circ\text{C}$
- Automatic Pressure Control
- FP: 0.47 inch $\sim$ 2.7 inch size,  
BP: 3.9 inch size available

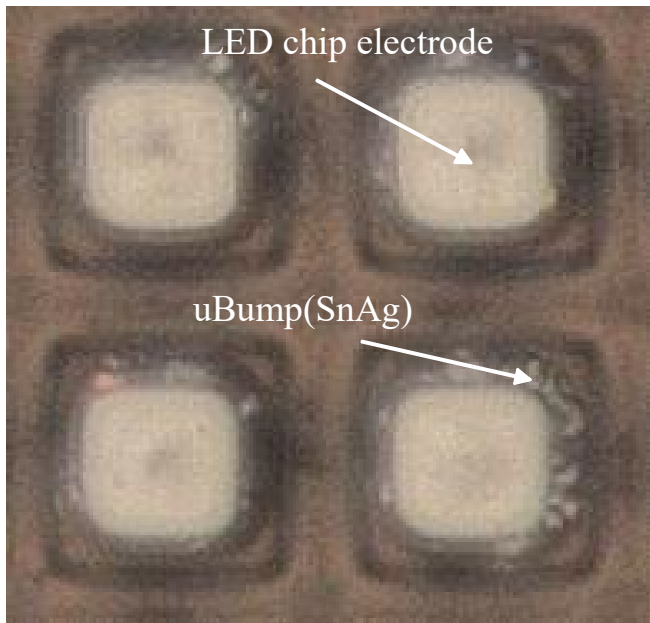
**- Suitable to produce the small panels with high PPI for watch and VR**



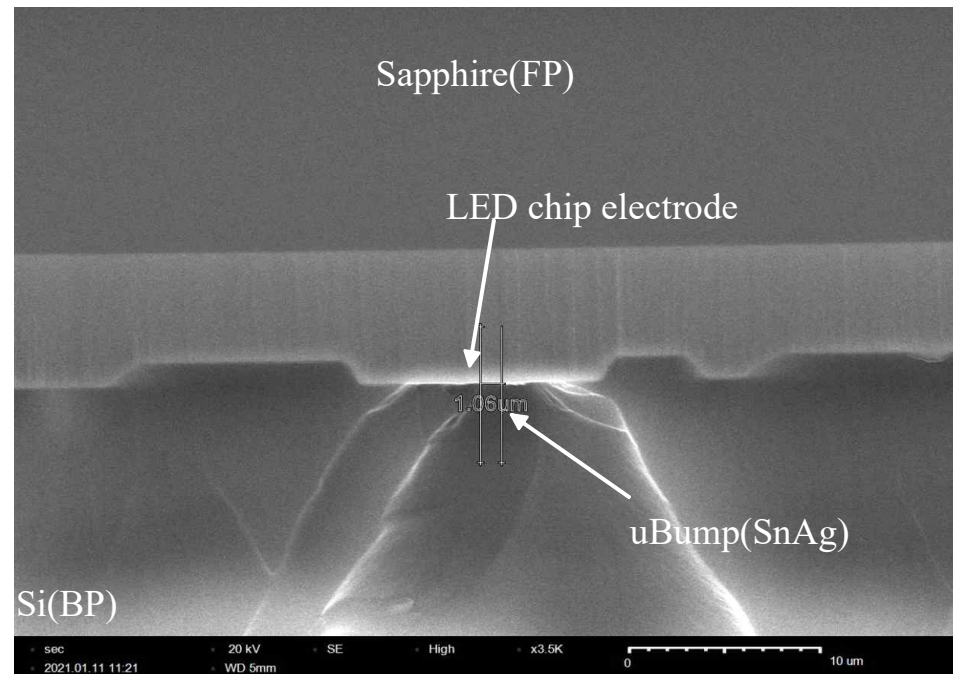
# Process Results



## Eutectic Bonding(laser & thermal)



## Align Accuracy Performance: 1.06um





*Thank you!*

- *Phone* : +82-31-646-1500
- *Fax* : +82-31-646-1515
- *Email* : [sales@kosteks.com](mailto:sales@kosteks.com)
- *Web site* : [www.kosteks.com](http://www.kosteks.com)